

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**

## BEST AVAILABLE COPY

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-031349

(43)Date of publication of application : 28.01.2000

(51)Int.Cl.

H01L 23/29

H01L 23/31

G01L 9/04

G01P 15/08

H01L 21/60

(21)Application number : 11-066948

(71)Applicant : DENSO CORP

(22)Date of filing : 12.03.1999

(72)Inventor : YOSHIHARA SHINJI  
INOMATA SUMITOMO  
ATSUMI KINYA  
SAKAI MINEICHI  
SHIMOYAMA YASUKI  
FUJII TETSUO

(30)Priority

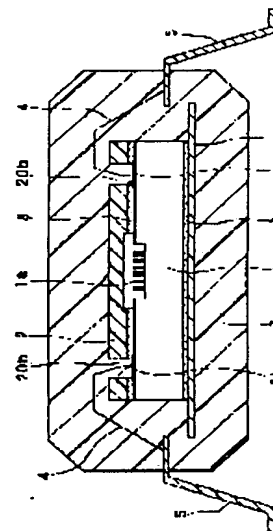
Priority number : 10067276 Priority date : 17.03.1998 Priority country : JP

## (54) SEMICONDUCTOR DEVICE AND MANUFACTURE OF IT

(57)Abstract:

PROBLEM TO BE SOLVED: To eliminate the problem caused by intrusion of a cutting water at dicing, related to a semiconductor acceleration sensor comprising a protective cap.

SOLUTION: A heat-resistant resin sheet 2 is used as a protective cap which protects a beam structure body 1a formed at a semiconductor chip 1, while the heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with a heat-resistant bonding agent 3. A polyimide base material is used as the heat-resistant resin sheet 2 while a silicon adhesive agent is used as the heat-resistant bonding agent 3. The heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with the heat-resistant bonding agent 3 like this so that such a problem as intrusion of cutting water is avoided at dicing cut.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

**BEST AVAILABLE COPY**

[Date of registration]

[Number of appeal against examiner's decision  
of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2000 Japan Patent Office